



SMD Mount Receptacle

Part No:

RECE.20449.001E.01

Description:

SMD HSC Compatible Receptacle

Compatible with I-PEX MHF [®]4. I-PEX MHF [®]4L, and Murata HSC

Features:

Mating Height: 1.2mm Max

15000pcs per reel

Dimensions: 2 x 2 x 0.6 mm

Diameter: 1.4mm

RoHS & Reach Compliant



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Ireland & USA ISO 9001:2015 Certified



Taiwan ISO 9001:2015 Certified















Part of the Taoglas SMD Mount Receptacle, the RECE.20449.001E.01 is a 3-pad type wire-to-board SMD Receptacle solution that is ultra-small, lightweight, and low profile, 1.6mm max. with an operational frequency range of DC to 8 GHz the RECE.20449.001E.01 is gold plated to provide superior performance and allow easy mounting of the male RF connector.

Packaged on tape and reel, this receptacle is designed to be placed with automatic "pick and place" equipment for ease of installation.

The RECE.20449.001E.01 acts as a 50 Ohm transmission line to connect the micro-miniature RF connector to the printed circuit board. It is fully compatible with I-PEX MHF [®]4, I-PEX MHF [®]4L, Murata HSC and all other available HSC compatible connectors.

Applicable Technologies:

The RECE.20449.001E.01 receptacles are commonly integrated into GSM module, GPS module, Wireless LAN modules. Many 5G modules are currently using these compatible receptacles for the next generation of cellular applications.

For further information, please contact your regional Taoglas customer support team.



2. Specifications

Electrical		
Operation Frequency	DC to 8 GHz	
VCMD	1.2 Max at DC~3 GHz	
VSWR	1.3 Max at 3~8 GHz	
Nominal Impedance	50 Ohm	
Rated Voltage	60V AC	
Rated Current	1A Max.	
Contact Resistance	Subject mated contacts assembled in housing to 20mV Max. open circuit at 10mA Max	
Withstand Voltage	AC 200V/minute	
Insulation Resistance	Impressed voltage 100V DC for 1min Initial : $500M\Omega$ Min. Final : $100M\Omega$ Min.	
Dielectric Withstanding Voltage	200V AC for 1 minute	
Current leakage	0.5mA Max	
Temperature	-40 to +90°C	

Material	
Outer Contact	Copper Alloy (Au plating)
Centre Contact	Copper Alloy (Au plating)
Insulator	LCP UL94-V0

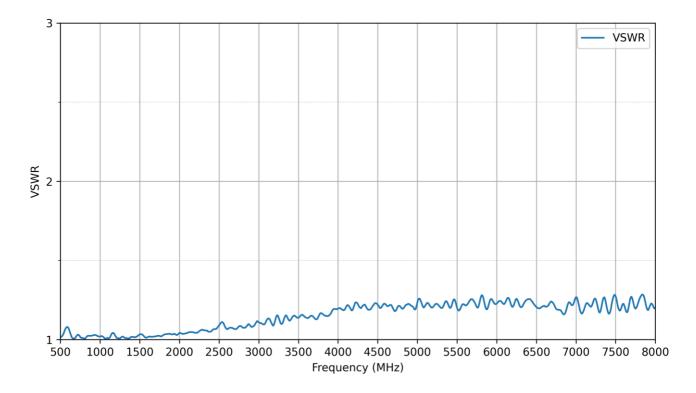


Environmental			
Durability per EIA-364-09C (2-3 cycles per min @ 30 cycles)			
Vibration	10Hz -> 100Hz -> 10Hz for 20 mins.		
Peak value of acceleration	1.5mm or 59m/s2 (6G)		
Direction	3 axis 3 Cycles		
Mechanical Shock			
Accelerate Velocity	735m/s2 (75G)		
Waveform	Half-sine shock plus.		
Duration	11m sec.		
Direct Current	1mA		
Direction	In ±X, ±Y and ±Z axes.		
Cycle	3 cycles for each direction, totally 18 cycles		
Thermal Shock (40°C for 30mins to 5~35°C for 5 minutes to 90°C for 30mins to 5~35°C for 5 minutes)			
Transition Time	5 minutes		
Cycles	5		
Humidity	90~95% RH		
Temperature	40+/- 2°C		
Duration	96 hours		
	Salt Water Spray		
Temperature	35+/- 2°C		
Salt Water Density	5+/-1% (by weight)		
Duration	48 Hours		
High temperature life	90+/- 2°C for 96 hours		
Cold temperature life	-40+/- 2°C for 96 hours		
	H2S gas		
Temperature	40+/-2°C		
Relative Humidity	80 +/-5% RH		
Gas H2S	3+/-1 ppm		
Duration	96 Hours		
Moister Sensitivity Level	2		

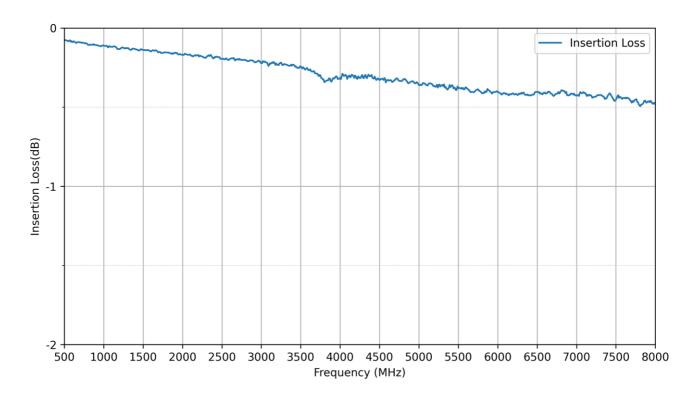


3. Connector Data

3.1 VSWR

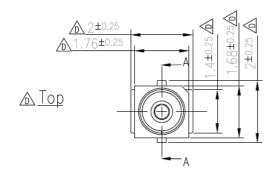


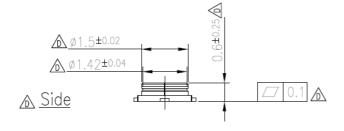
3.2 Insertion Loss

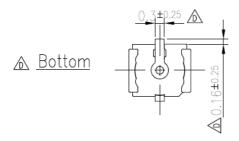


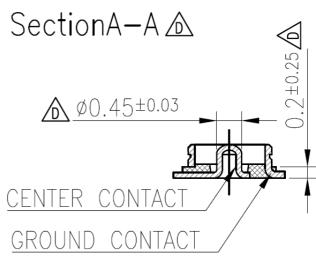


4. Mechanical Drawing (Units: mm)



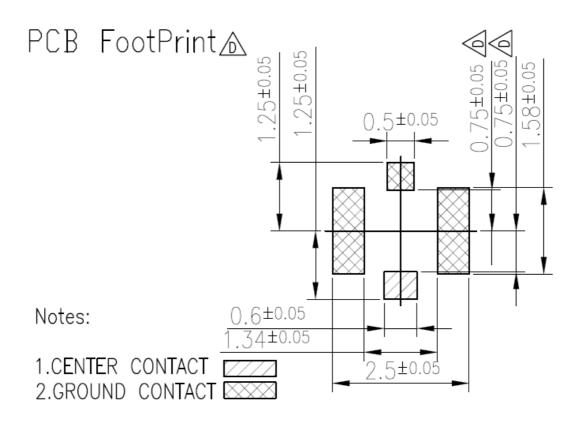








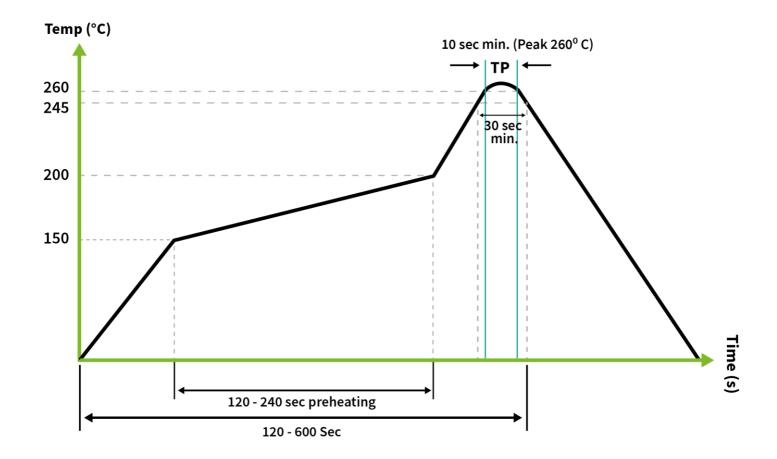
5. Footprint





6. Solder Reflow

The RECE.20449.001E.01 can be assembled by following the recommended soldering temperatures are as follows:



*Temperatures listed within a tolerance of +/- 10º C

Smaller components are typically mounted on the first pass, however, we do advise mounting the RECE.20449.001E.01 when placing larger components on the board during subsequent reflows.

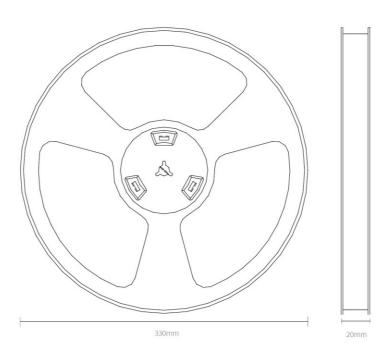
Note: Soldering flux classified ROLO under IPC J-STD-004 is recommended.

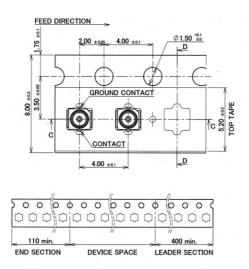


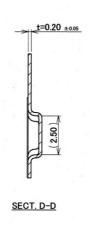
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7. Packaging

15000 pcs RECE.20449.001E.01 reel Dimensions - 330*330*20mm





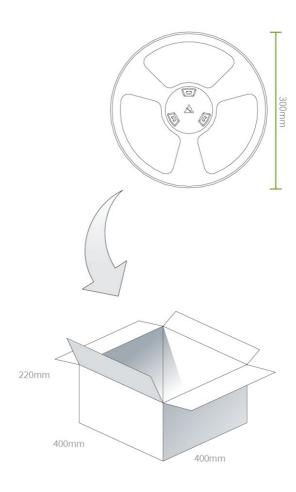




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15000 pcs RECE.20449.001E.01 reel Dimensions - 330*330*20mm

10 reels, 150000 pcs in one carton Carton Dimensions - 400*400*220mm





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Changelog for the datasheet

SPE-16-8-034 - RECE.20369.001E.01

	025-02-24 Ipdated graphs to show up to 8GHz.
Changes: U	Indated graphs to show up to 8GHz
	paated graphs to show up to ourse.
Changes Made by: G	ary West

Previous Revisions

Revision: I		
Date:	2024-10-28	
Changes:	Updated MSL from 3 to 2	
Changes Made by:	Paul Liu	

Revision: D		
Date:	2022-03-08	
Changes:	Updated Packaging	
Changes Made by:	Gary West	

Revision: H		
Date:	2023-09-07	
Changes:	Updated Solder Reflow Information	
Changes Made by:	Cesar Sousa	

Revision: C		
Date:	2021-07-15	
Changes:	Updated Solder Reflow Diagram & Adding MSL.	
Changes Made by:	Gary West	

Revision: G		
Date:	2023-03-03	
Changes:	Updated specifications	
Changes Made by:	Cesar Sousa	

Revision: B		
Date:	2021-02-03	
Changes:	Following EC-20-8-036	
Changes Made by:	Jack Conroy	

Revision: F	
Date:	2022-01-27
Changes:	Updated specifications
Changes Made by:	Cesar Sousa

Revision: A (Original First Release)	
Date:	2016-04-21
Notes:	
Author:	Jack Conroy

Revision: E	
Date:	2022-07-05
Changes:	Updated drawing
Changes Made by:	Cesar Sousa





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